

# NC7SZ04 TinyLogic<sup>®</sup> UHS Inverter

### **Features**

- Ultra-High Speed: t<sub>PD</sub> 2.4ns (Typical) into 50pF at 5V V<sub>CC</sub>
- High Output Drive: ±24mA at 3V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65V to 5.5V
- Matches Performance of LCX when Operated at 3.3V V<sub>CC</sub>
- Pow er Dow n High Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5V to 3V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages
- Space-Saving SOT23 and SC70 Packages

### **Description**

The NC7SZ04 is a single inverter from ON Semiconductor's Ultra-High Speed (UHS) series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive while maintaining low static power dissipation over a broad  $V_{\rm CC}$  operating range. The device is specified to operate over the 1.65V to 5.5V  $V_{\rm CC}$  operating range. The inputs and output are high-impedance when  $V_{\rm CC}$  is 0V. Inputs tolerate voltages up to 6V, independent of  $V_{\rm CC}$  operating voltage.

## **Ordering Information**

Part Number	Top Mark	Package	Packing Method
NC7SZ04M5X	7Z04	5-Lead SOT23, JEDEC MO-178 1.6mm	3000 Units on Tape & Reel
NC7SZ04P5X	Z04	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3000 Units on Tape & Reel
NC7SZ04L6X	CC	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
NC7SZ04FHX	CC	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

# **Connection Diagrams**

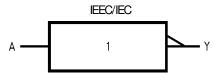
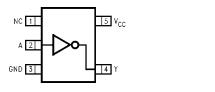


Figure 1. Logic Symbol

# **Pin Configurations**





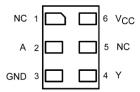


Figure 3. MicroPak™ (Top Through View)

# **Pin Definitions**

Pin # SC70 / SOT23	Pin # MicroPak™	Name	Description
1	1,5	NC	No Connect
2	2	Α	Input
3	3	GND	Ground
4	4	Υ	Output
5	6	V <sub>CC</sub>	Supply Voltage

# **Function Table**

Y = /A

Inputs	Output
Α	Υ
L	Н
Н	L

H = HIGH Logic Level

L = LOW Logic Level

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Par	ameter	Min.	Max.	Unit	
V <sub>CC</sub>	Supply Voltage	-0.5	6.0	V		
V <sub>IN</sub>	DC Input Voltage		-0.5	6.0	V	
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.0	V	
	DC Input Diode Current	V <sub>IN</sub> < -0.5V		-50	mA	
l <sub>IK</sub>	Do input blode current	$V_{IN} > 6.0V$		+20	IIIA	
	DC Output Diode Current	V <sub>OUT</sub> < -0.5V		-50	- mA	
Юк	Do Output Diode Current	$V_{OUT} > 6V, V_{CC} = GND$		+20	IIIA	
l <sub>out</sub>	DC Output Current		±50	mA		
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current		±50	mA		
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C	
TJ	Junction Temperature Under Bia	as		+150	°C	
T <sub>L</sub>	Junction Lead Temperature (So	ldering, 10 Seconds)		+260	°C	
		SOT-23		200		
D	Dow or Discipation at 1959C	SC70-5		150	mW	
$P_{D}$	Pow er Dissipation at +85°C	MicroPak™-6		130	TIIVV	
		MicroPak2™-6		120		
ESD	Human Body Model, JEDEC:JES	D22-A114		4000	V	
ESD	Charge Device Model, JEDEC:JE	SD22-C101		2000		

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. ON Semiconductor does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V	Supply Voltage Operating		1.65	5.50	V
V <sub>CC</sub>	Supply Voltage Data Retention		1.5	5.5	] v
V <sub>IN</sub>	Input Voltage		0	5.5	٧
V <sub>OUT</sub>	Output Voltage		0	V <sub>cc</sub>	٧
T <sub>A</sub>	Operating Temperature		-40	+85	°C
		V <sub>CC</sub> at 1.8V, 2.5V ±0.2V	0	20	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Times	V <sub>CC</sub> at 3.3V ± 0.3V	0	10	ns/V
		V <sub>CC</sub> at 5.0V ± 0.5V	0	5	

0		SOT-23	300	
	Thermal Resistance	SC70-5	425	°C/W
$\theta_{\sf JA}$		MicroPak™-6	500	C/VV
		MicroPak2™-6	560	

### Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

# **DC Electrical Characteristics**

0	B	.,	0	1	Γ <sub>A</sub> =25°(	)	T <sub>A</sub> =-40	to 85°C	Units
Symbol	Parameter	V <sub>cc</sub>	Conditions	Min.	Тур.	Max.	Min.	Max.	Oilles
.,	HIGH Level Input	1.65 to 1.95		0.75V <sub>CC</sub>			0.75V <sub>CC</sub>		.,
V <sub>IH</sub> Voltage		2.30 to 5.50		0.70V <sub>CC</sub>			0.70V <sub>CC</sub>		V
.,	LOW Level Input	1.65 to 1.95				0.25V <sub>CC</sub>		0.25V <sub>CC</sub>	.,
$V_{IL}$	Voltage	2.30 to 5.50				0.30V <sub>CC</sub>		0.30V <sub>CC</sub>	V
		1.65		1.55	1.65				
		1.80		1.70	1.80		1.70		
		2.30	$V_{IN}=V_{IL}$ , $I_{OH}=-100\mu A$	2.20	2.30		2.20		
V <sub>он</sub>		3.00		2.90	3.00		2.90		
	HIGH Level	4.50		4.40	4.50		4.40		V
	Output Voltage	1.65	I <sub>OH</sub> =-4mA	1.29	1.52		1.29		
		2.30	I <sub>OH</sub> =-8mA	1.90	2.15		1.90		
		3.00	I <sub>OH</sub> =-16mA	2.40	2.80		2.40		
		3.00	I <sub>OH</sub> =-24mA	2.30	2.68		2.30		
		4.50	I <sub>OH</sub> =-32mA	3.80	4.20		3.80		
		1.65			0.00	0.10		0.10	
		1.80			0.00	0.10		0.10	
		2.30	$V_{IN}=V_{IH}$ , $I_{OL}=100\mu A$		0.00	0.10		0.10	
		3.00			0.00	0.10		0.10	
V	LOW Level	4.50			0.00	0.10		0.10	V
$V_{OL}$	Output Voltage	1.65	I <sub>OL</sub> =4mA		0.80	0.24		0.24	
		2.30	I <sub>OL</sub> =8mA		0.10	0.30		0.30	
		3.00	I <sub>OL</sub> =16mA		0.15	0.40		0.40	
		3.00	I <sub>OL</sub> =24mA		0.22	0.55		0.55	
		4.50	I <sub>OL</sub> =32mA		0.22	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	0 to 5.5	$0 \leq V_{IN} \! \leq 5.5V$			±1		±10	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	0	V <sub>IN</sub> or V <sub>OUT</sub> =5.5V			1		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	1.65 to 5.50	V <sub>IN</sub> =5.5V, GND			2.0		20	μΑ

### **AC Electrical Characteristics**

Symbol	Parameter	Paramotor V	Conditions	T <sub>A</sub> =25°C		T <sub>A</sub> =-40	to 85°C	Units	Figure	
Symbol	Parameter	V <sub>cc</sub>	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	rigure
		1.65		2.0	5.3	11.4	2.0	12.0		
		1.80		2.0	4.4	9.5	2.0	10.0		
	Propagation Delay	2.50 ± 0.20	$C_L=15pF,$ $R_L=1M\Omega$ $C_L=50pF,$	0.8	2.9	6.5	0.8	7.0		
t <sub>PLH</sub> , t <sub>PHL</sub>		3.30 ± 0.30		0.5	2.1	4.5	0.5	4.7		Figure 4 Figure 5
		5.00 ± 0.50		0.5	1.8	3.9	0.5	4.1		
		3.30 ± 0.30		<sub>=50pF</sub> , 1.5 2.9 5.0 1.5 5.2						
		5.00 ± 0.50	R <sub>L</sub> =500Ω	0.8	2.4	4.3	0.8	4.5	1	
C <sub>IN</sub>	Input Capacitance	0.00			4				pF	
	Power Dissipation	3.30			20		·		5E	Eiguro 6
$C_{\mathtt{PD}}$	Capacitance <sup>(2)</sup>	5.00			26				pF	Figure 6

#### Note:

2.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption ( $I_{CCD}$ ) at no output lading and operating at 50% duty cycle.  $C_{PD}$  is related to  $I_{CCD}$  dynamic operating current by the expression:  $I_{CCD}$ =( $C_{PD}$ )( $V_{CC}$ )( $f_{IN}$ )+( $I_{CC}$ )static).

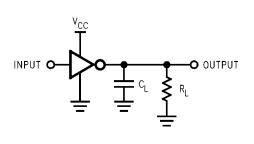


Figure 4. AC Test Circuit

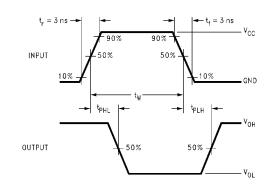
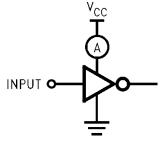


Figure 5. AC Waveforms



#### Note:

3. Input=AC Waveform;  $t_r=t_f=1.8$ ns; PRR=10MHz; Duty Cycle=50%.

Figure 6. I<sub>CCD</sub> Test Circuit

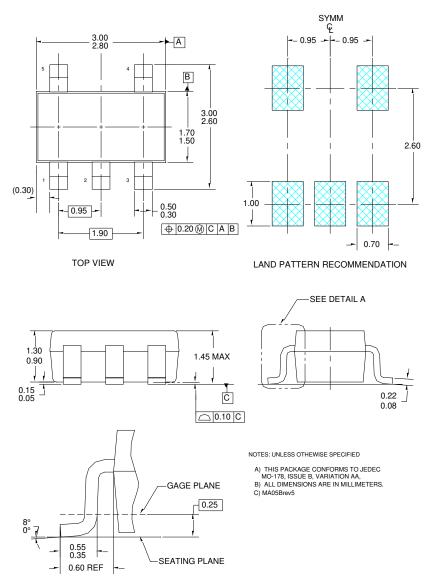


Figure 7. 5-Lead SOT23, JEDEC MO-178 1.6mm

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Package Designator	ckage Designator Tape Section		Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
M5X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

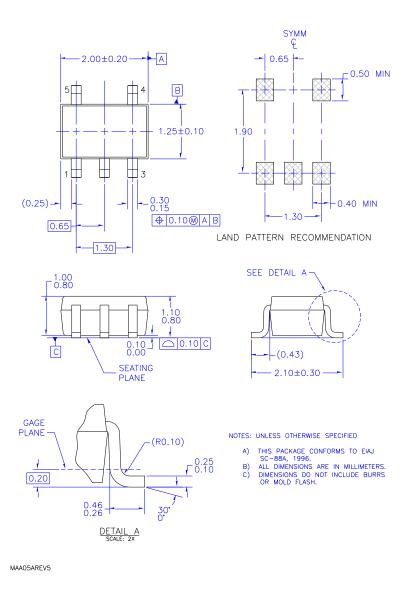
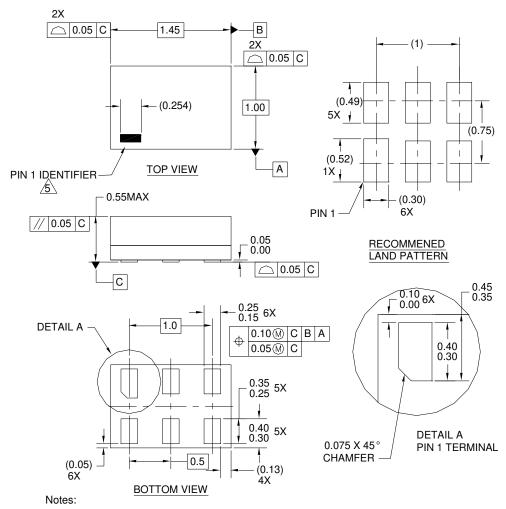


Figure 8. 5-Lead, SC70, EAJ SC-88a, 1.25mm Wide

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	Trailer (Hub End)	75 (Typical)	Empty	Sealed	



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- 5 PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

OTHER LINE IN THE MARK CODE LAYOUT.

Figure 9. 6-Lead, MicroPak™, 1.0mm Wide

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		Trailer (Hub End)	75 (Typical)	Empty	Sealed

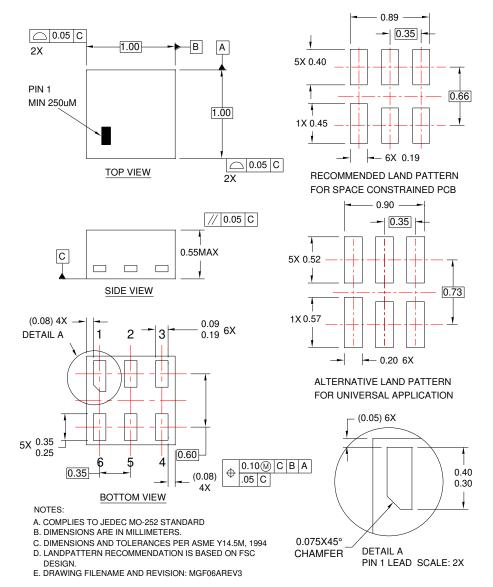


Figure 10. 6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch

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FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

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